

APPLICATIONS



CONSUMER



INDUSTRIAL



AUTOMOTIVE

MEMS & SENSOR PACKAGING TYPE	OVERMOLD			MOLDED EXPOSED DIE		CAVITY / LID PACKAGES		
	Inertial Accl, IMU	Magnetic	Current	Pressure	Humidity	Pressure	Humidity	Gas
STANDARD JEDEC PACKAGES	 	 	 		 		 	
CUSTOMIZED PACKAGES						 		
SUBSTRATE BASED PACKAGES (MIS / BGA / LGA / CERAMIC)	 							